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# A Structure For Increasing Mobility In A High-Electron-Mobility Transistor

Tech ID: 27402 / UC Case 2017-462-0

## **BRIEF DESCRIPTION**

A technique that results in a significant increase of electron mobility and sheet charge density at small channel thickness.

# **BACKGROUND**

HEMTs are solid-state electron devices made from a semiconductor heterostructure used to amplify high-frequency signals. Electron mobility is important to device performance and so it is extremely desirable to discover ways to improve electron mobility.

## **DESCRIPTION**

Researchers at the University of California, Santa Barbara have created a channel structure for semiconductor highelectron mobility transistors (HEMTs) that results in a significant increase of electron mobility and sheet charge density at small channel thickness. This enables the fabrication of devices with increased high frequency power performance and allows for better lateral and vertical scalability.

# **ADVANTAGES**

- ► Increased electron mobility
- ► Improved device performance (94 GHz)

# **APPLICATIONS**

- ► High-electron mobility transistors
- ► Power electronics

## CONTACT

Available Technologies

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#### **INVENTORS**

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## **OTHER INFORMATION**

# **KEYWORDS**

Semiconductor, Transistor,

High Electron Mobility, HEMT,

indfeat, indpowerelec

## **CATEGORIZED AS**

- **►** Nanotechnology
  - ▶ Electronics
- **▶** Semiconductors
  - Design and

**Fabrication** 

# **RELATED CASES**

2017-462-0

Country	Туре	Number	Dated	Case
United States Of America	Issued Patent	11,101,379	08/24/2021	2017-462

# ADDITIONAL TECHNOLOGIES BY THESE INVENTORS

- ► (In,Ga,AI)N Optoelectronic Devices with Thicker Active Layers for Improved Performance
- ► GaN-based Vertical Metal Oxide Semiconductor and Junction Field Effect Transistors
- ▶ Iii-N Transistor With Stepped Cap Layers
- ▶ III-N Based Material Structures and Circuit Modules Based on Strain Management

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